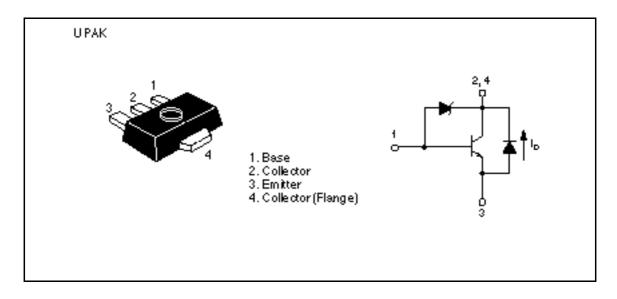
Silicon NPN Epitaxial

HITACHI

Application

Low frequency power amplifier

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	25	V
Collector to emitter voltage	V_{CEO}	25	V
Emitter to base voltage	V_{EBO}	6	V
Collector current	I _c	0.8	А
Collector peak current	ic _(peak)	1.5	А
E to C diode forward current	I _D	0.6	A
Collector power dissipation	P _c *1	1.0	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

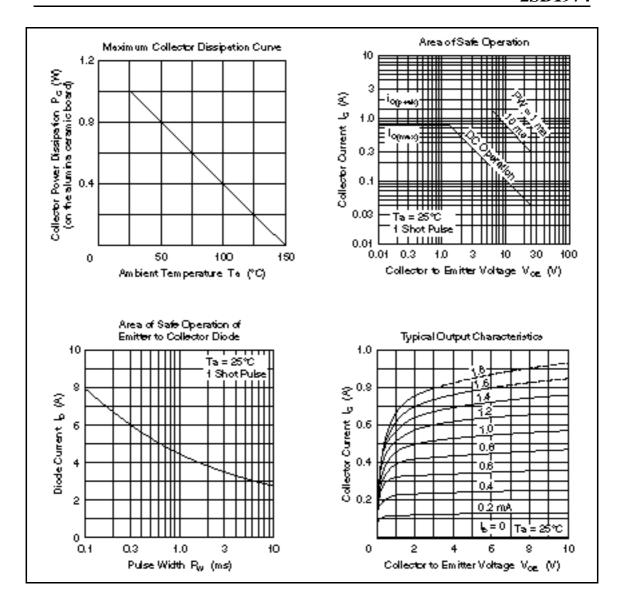
Note: 1. Value on the alumina ceramic board (12.5 x 20 x 0.7 mm)

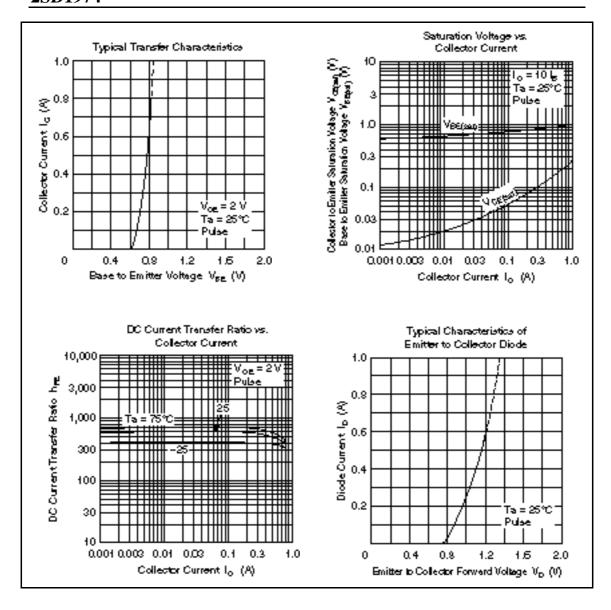
Electrical Characteristics ($Ta = 25^{\circ}C$)

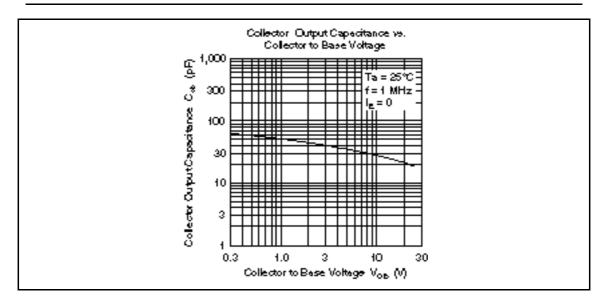
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	_	_	V	$I_{c} = 10 \ \mu A, \ I_{e} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	25	_	35	V	$I_C = 1 \text{ mA}, R_{BE} =$
Collector to emitter sustaining voltage	$V_{\text{CEO(sus)}}$	25	_	35	V	$I_{C} = 0.8 \text{ A}, R_{BE} = ,$ L = 20 mH
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}		_	0.2	μΑ	$V_{CB} = 20 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	0.5	μΑ	V_{CE} = 20 V, R_{BE} =
Emitter cutoff current	I _{EBO}	_	_	0.2	μΑ	$V_{EB} = 5 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE}	250	_	1200		$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.4	V	$I_{\rm C} = 0.8 \text{ A}, I_{\rm B} = 80 \text{ mA}^{*1}$
E to C diode forward voltage	$V_{\scriptscriptstyle D}$	_		1.5	V	$I_D = 0.6 A^{*1}$
-	•		•		·	

Notes: 1. Pulse test

2. Marking is "ES".







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